

NOTES

- ▲ MATERIAL
- 1.HOUSING MATERIAL: LCP BLACK UL94V-0.
 - 2.CONTACT MATERIAL: COPPER ALLOY T=0.25MM.
 - 3.PLATING: GOLD PLATING ON CONTACT AREA AND TIN PLATING ON SOLDER AREA OVER NICKEL.

- 4.SHIELD: SUS T=0.20mm WITH NICKEL PLATED.
- 5.BOTTOM SHIELD: SUS T=0.15mm .

ELECTRICAL

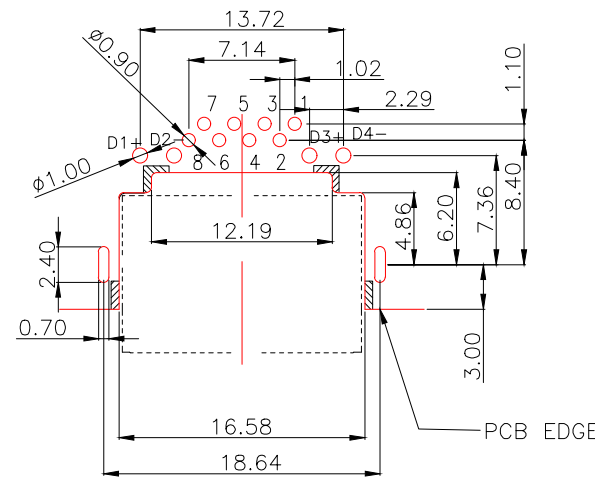
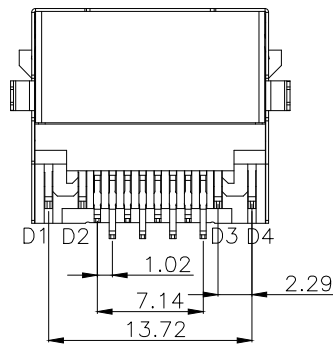
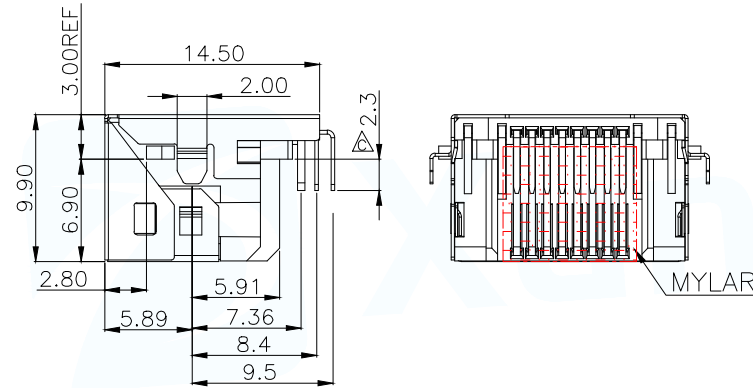
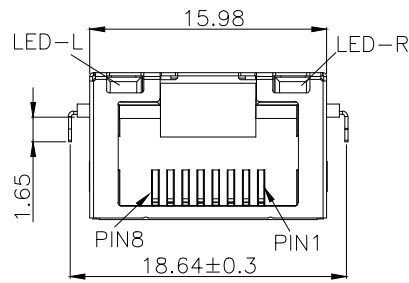
- 1.VOLTAGE RATING: 125 VAC RMS.
- 2.CURRENT RATING: 1.5 AMP.
- 3.CONTACT RESISTANCE: 40 MILLIOHMS MAX.
- 4.INSULATION RESISTANCE: 500 MEGOHMS MIN @ 100V DC .
- 5.DIELECTRIC DIELECTRIC RESISTANCE: 500V DC RMS 50Hz. 1MIN.

MECHANICAL

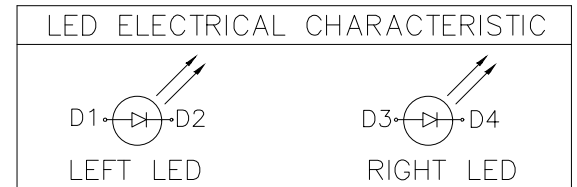
- 1.DURRABILITY: 750 CYCLES MIN.
- 2.MATING/UNMATING FORCE: 2.24 KG.F MAX.

ENVIRONMENTAL:

- 1.STORAGE: -40℃~+85℃.
- 2.OPERATION: -40℃~+85℃.



RECOMMENDED PCB LAYOUT
(t=1.6mm,tol:±0.05)



MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: RJ45 9.9H沉板3.0 18.64壳脚带灯
			PAR RJ45-005-003-11
DECIMALS:	ANGLES:		DWN
.X:±0.35	X':±3'		CHKD
.XX:±0.25	.X':±2'	APVD	
.XXX:±0.15	.XX':±1'	CUSTOMER COPY	SCALE:1:1 UNIT:MM
		SIZE:A4	SHEET:1F1
			REV:A